



Material Content Data Sheet



Sales Product Name		BTT6200-1EJA		Issued		3. July 2019		
MA#		MA005337210						
Package		PG-DSO-8-43		Weight*		83.99 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.977	1.16	1.16	11629	11629
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		112	
	non noble metal	zinc	7440-66-6	0.038	0.04		448	
	non noble metal	iron	7439-89-6	0.752	0.90		8952	
	non noble metal	copper	7440-50-8	30.529	36.35	37.30	363495	373007
wire	non noble metal	copper	7440-50-8	0.193	0.23	0.23	2296	2296
encapsulation	organic material	carbon black	1333-86-4	0.099	0.12		1179	
	plastics	epoxy resin	-	4.554	5.42		54219	
	inorganic material	silicondioxide	60676-86-0	44.844	53.41	58.95	533942	589340
leadfinish	non noble metal	tin	7440-31-5	0.814	0.97	0.97	9690	9690
plating	noble metal	silver	7440-22-4	0.726	0.86	0.86	8644	8644
glue	plastics	epoxy resin	-	0.079	0.09		944	
	noble metal	silver	7440-22-4	0.374	0.44	0.53	4450	5394
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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